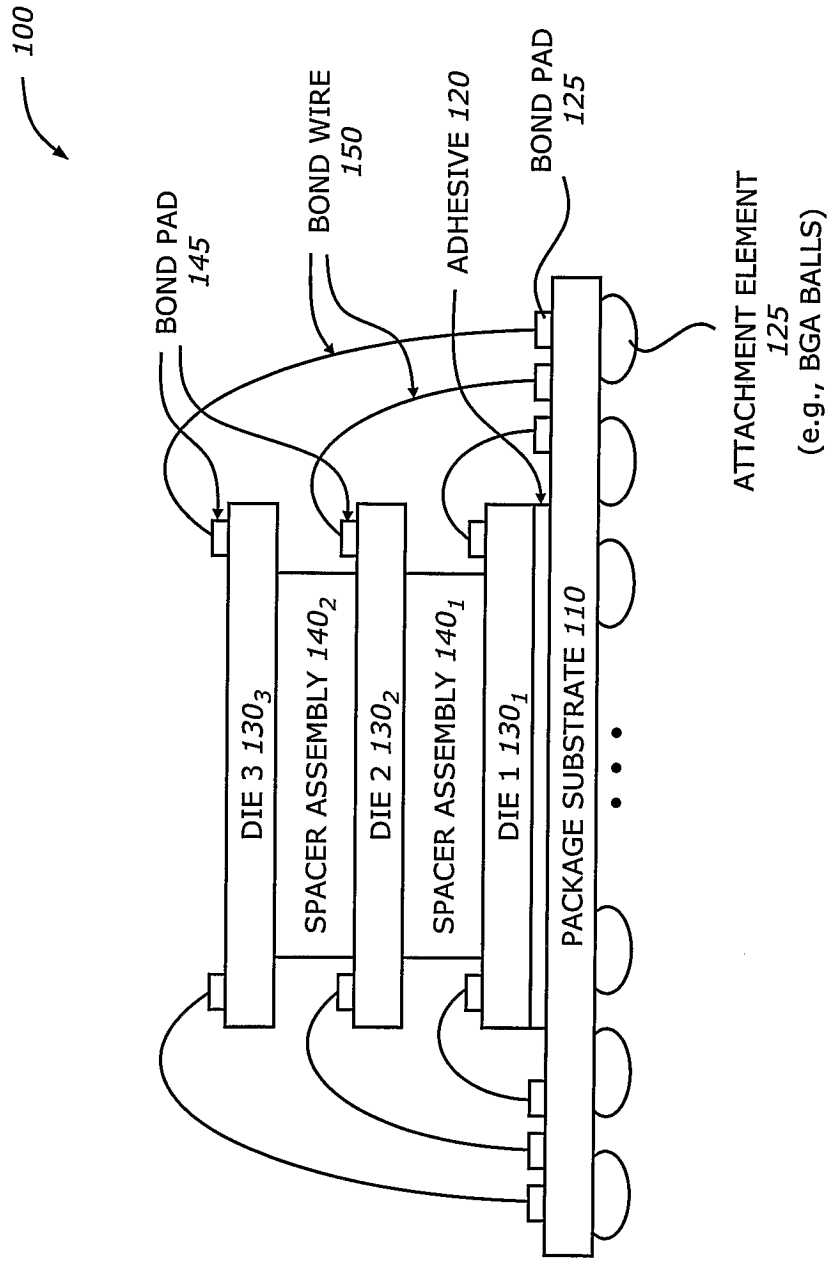

100
BOND PAD 145
BOND WIRE 150
ADHESIVE 120
BOND PAD 125
ATTACHMENT ELEMENT 125 (e.g., BGA BALLS)
DIE 3 130_3
SPACER ASSEMBLY 140_2
DIE 2 130_2
SPACER ASSEMBLY 140_1
DIE 1 130_1
PACKAGE SUBSTRATE 110

FIG. 1

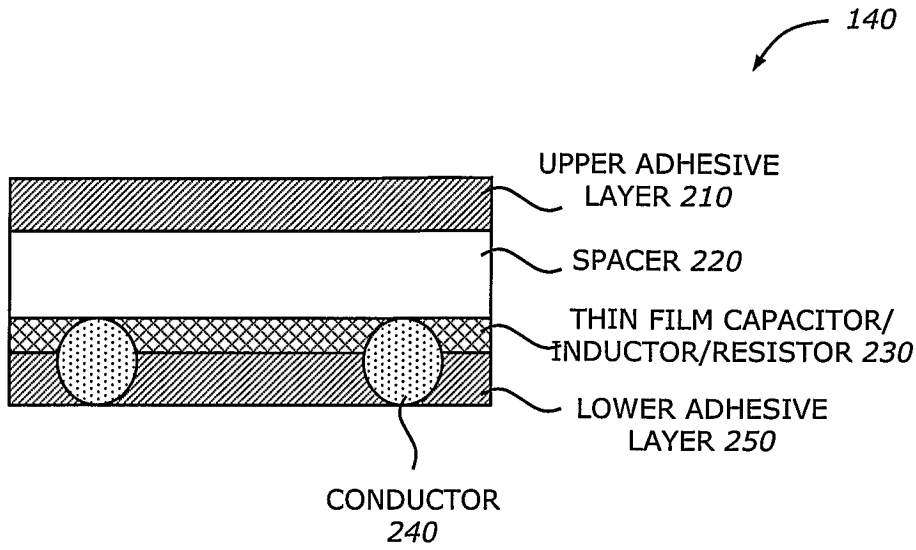

140
UPPER ADHESIVE LAYER 210
SPACER 220
THIN FILM CAPACITOR/ INDUCTOR/RESISTOR 230
LOWER ADHESIVE LAYER 250
CONDUCTOR 240

FIG. 2

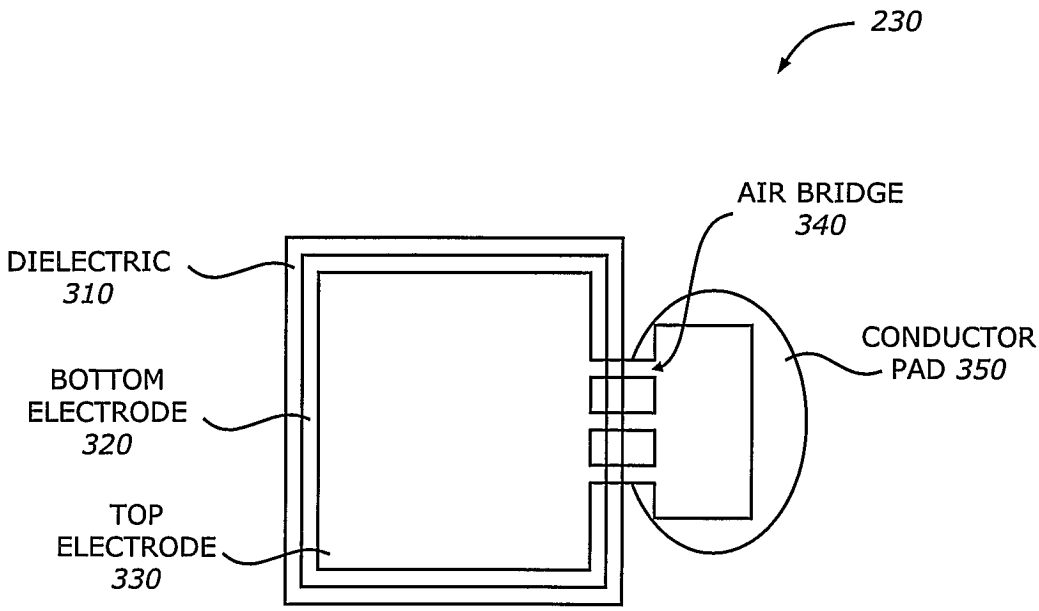

230
AIR BRIDGE 340
DIELECTRIC 310
CONDUCTOR PAD 350
BOTTOM ELECTRODE 320
TOP ELECTRODE 330

FIG. 3

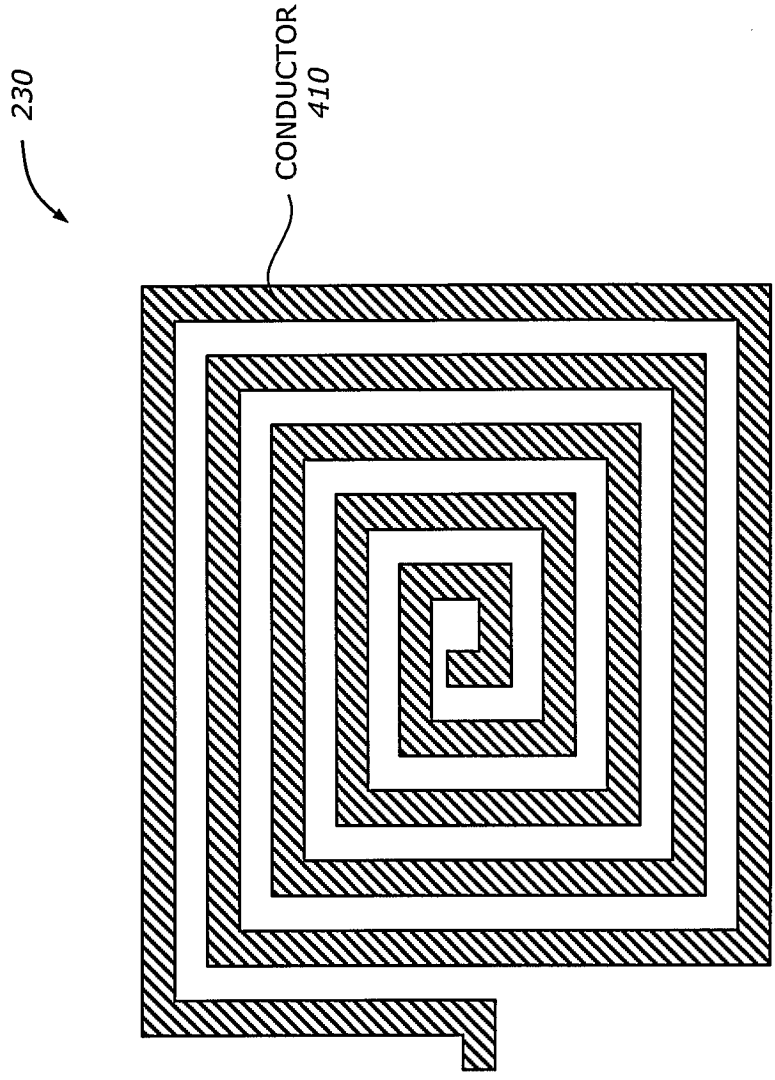


FIG. 4

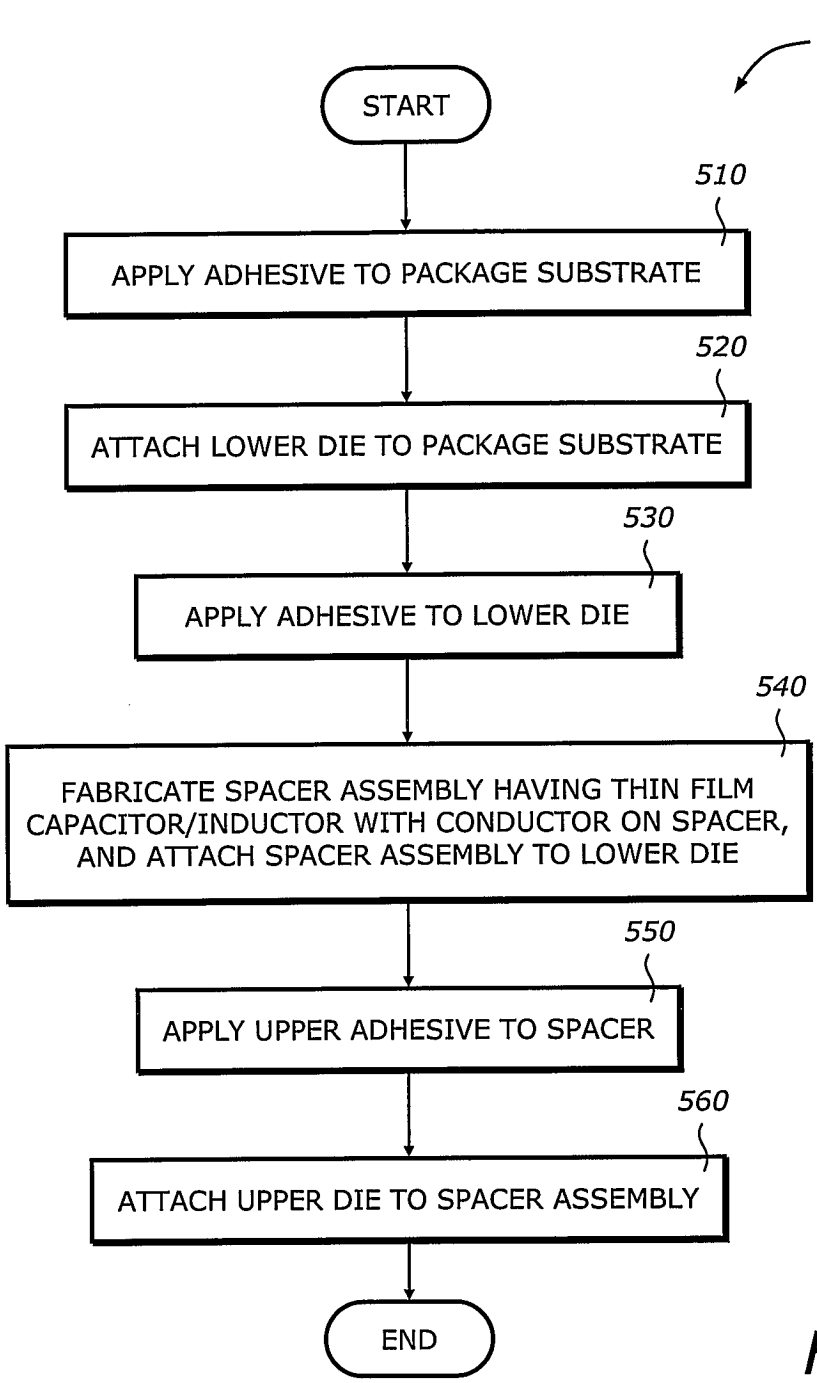

500
START
510
APPLY ADHESIVE TO PACKAGE SUBSTRATE
520
ATTACH LOWER DIE TO PACKAGE SUBSTRATE
530
APPLY ADHESIVE TO LOWER DIE
540
FABRICATE SPACER ASSEMBLY HAVING THIN FILM CAPACITOR/INDUCTOR WITH CONDUCTOR ON SPACER, AND ATTACH SPACER ASSEMBLY TO LOWER DIE
550
APPLY UPPER ADHESIVE TO SPACER
560
ATTACH UPPER DIE TO SPACER ASSEMBLY
END

FIG. 5

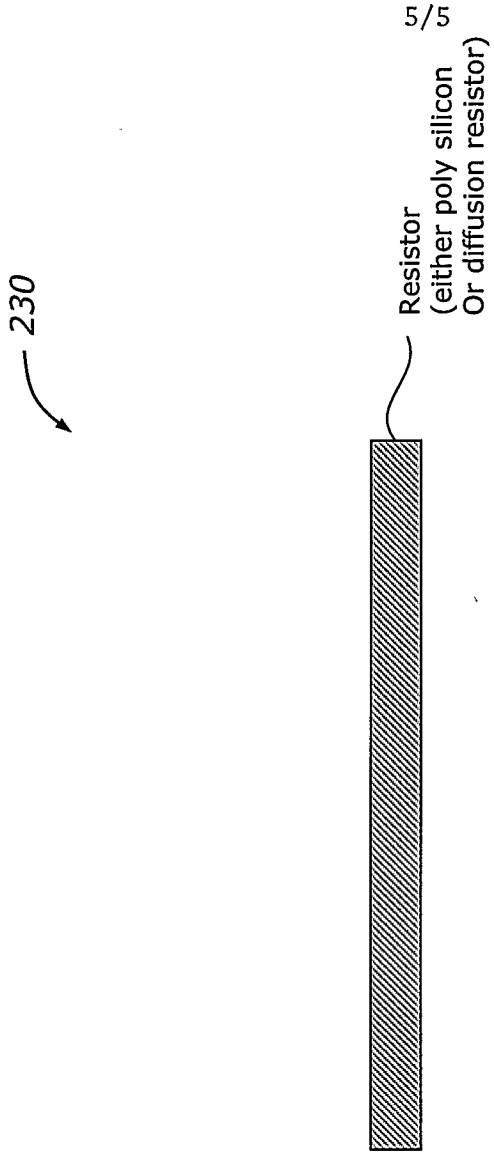


FIG. 6